Compare

Intel® Wireless Products Intel® Wireless 7200

Products formerly Stone

Learn how Intel is pursuing conflict-free technology. >

Export Full Specifications > Support Overview > Search Distributors >

PCN/MDDS Information

939178: PCN | MDDS 939183: PCN | MDDS 939184: PCN | MDDS

Related Products

Series

Peak

Quick Links





Type Here to Search Products





Intel® Dual Band Wireless-N 7265

Specifications	^
Essentials	
Networking Specifications	
Package Specifications	
Advanced Technologies	

Ordering / sSpecs / **Steppings**

Specifications		
- Essentials		
Status	Launched	
Launch Date	Q3'14	
Board Form Factor	M.2 2230, 1216	
Weight (in grams)	2.4	
Operating Temperature Range	0°C to 80°C	
Supported Operating Systems	Microsoft Windows 7 Microsoft Windows 8/8.1 Linux	
Antenna	2x2	
Product Brief	Link	
Conflict Free	Yes	

Board Form Factor	M.2 2230, 1216
Weight (in grams)	2.4
Operating Temperature Range	0°C to 80°C
Supported Operating Systems	Microsoft Windows 7 Microsoft Windows 8/8.1 Linux
Antenna	2x2
Product Brief	Link
Conflict Free	Yes
Networking Specifications	
TX/RX Streams	2x2
Bands	2.4 GHz, 5 GHz
Max Speed	300 Mbps
Wi-Fi CERTIFIED*	Yes
Compliance	FIPS, FISMA
Integrated Bluetooth	Yes
System Interface Type	PCIe, USB
- Package Specifications	
Package Size	22mm x 30mm, 12mm x 16mm
- Advanced Technologies	
Intel® Wireless Display	Yes
4G WiMAX Wireless Technology	No
Supported Under vPro	Yes

- Package Specifications	
Package Size	22mm x 30mm, 12mm x 16mm
- Advanced Technologies	
Intel® Wireless Display	Yes
4G WiMAX Wireless Technology	No
Supported Under vPro	Yes
Intel® Smart Connect Technology	Yes

All information provided is subject to change at any time, without notice. Intel may make changes to manufacturing life cycle, specifications, and product descriptions at any time, without notice. The information herein is provided "as-is" and Intel does not make any representations or warranties whatsoever regarding accuracy of the information, nor on the product features, availability, functionality, or compatibility of the products listed. Please contact system vendor for more information on specific products or systems.

"Intel classifications" consist of Export Control Classification Numbers (ECCN) and Harmonized Tariff Schedule (HTS) numbers. Any use made of Intel classifications are without recourse to Intel and shall not be construed as a representation or warranty regarding the proper ECCN or HTS. Your company may be the exporter of record, and as such, your company is responsible for determining the correct classification of any item at the time of export.

Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

"Conflict free" and "conflict-free" means "DRC conflict free", which is defined by the U.S. Securities and Exchange Commission rules to mean products that do not contain conflict minerals (tin, tantalum, tungsten and/or gold) that directly or indirectly finance or benefit armed groups in the Democratic Republic of the Congo (DRC) or adjoining countries. Intel also uses the term "conflict-free" in a broader sense to refer to suppliers, supply chains, smelters and refiners whose sources of conflict minerals do not finance conflict in the DRC or adjoining countries. Intel processors manufactured before January 1, 2013 are not confirmed conflict free. The conflict free designation refers only to product manufactured after that date. For Intel Boxed Processors, the conflict free designation refers to the processor only, not to any additional included accessories, such as heatsinks/coolers.

Send us your feedback!

Company Information Our Commitment Communities Investor Relations Contact Us





f y in 📅 🖸

© Intel Corporation | Terms of Use | *Trademarks | Privacy | Cookies | Supply Chain Transparency | Site Map